

AMENDMENT TO THE CLAIMS

1. (previously presented): A method for fabricating a slider comprising the steps of:
 fabricating a plurality of transducers on a wafer;
 slicing the wafer into slider bars having a plurality of sliders formed therealong and fabricating air bearing surfaces for the plurality of sliders along the slider bar; and
 etching a trench prior to slicing the wafer to form a trailing edge of the air bearing surfaces of the plurality of sliders.
2. (currently amended): The method of claim 1 and further comprising the step of:
 depositing an overcoat layer prior to slicing the wafer and forming the trench in the overcoat layer.
3. (original): The method of claim 1 wherein the air bearing surfaces of the plurality of sliders along the slider bar are formed using a photoalignment masking process.
4. (previously presented): The method of claim 1 wherein a recessed surface of the trench forms the trailing edge for the raised bearing surfaces of the sliders.
5. (original): The method of claim 1 and further comprising the step of:
 planarizing the slider or wafer prior to etching the trench.

Claims 6-10. (cancelled)

11. (currently amended): The head of claim 923 wherein the including a transducer portion proximate to the trailing edge including includes inductive and/or magnetoresistive transducer elements.

12. (currently amended): The head of claim 923 wherein the trench forms a trailing edge of a raised bearing surface of the slider.

13. (currently amended): The method of claim 622 wherein the trench is fabricated in a onefirst process step and comprising the step of:

fabricating a raised bearing surface and a recessed bearing surface on a dismedia facing surface of the slider in another second process step and the raised bearing surface in the othersecond process step having a trailing edge defined by the trench fabricated in the onefirst process step.

14. (currently amended): The method of claim 13 and further comprising the step of:

planarizing or lapping the dismedia facing surface of the slider in addition to the onefirst process step and the othersecond process step.

15. (currently amended): The method of claim 14 and further comprising the step of planarizing or lapping the dismedia facing surface of the slider prior to the othersecond process step and after the onefirst process step.

16. (currently amended): The method of claim 13 wherein the raised bearing surface and the recessed bearing surface are

formed using a photoalignment masking process in the ~~either~~second process step.

17. (currently amended): The method of claim 13 wherein the trench is etched in the ~~one~~first process step prior to forming the raised bearing surface and the recessed bearing surface in the ~~either~~second process step.

18. (currently amended): The method of claim 13 wherein the raised bearing surface and the recessed bearing surface and the trailing edge of the raised bearing surface are etched relative to different orthogonal surfaces of the slider in the ~~one~~first and the ~~either~~second process steps.

19. (currently amended): The method of claim 13 and further comprising:

etching the trench relative to a first orientation in the ~~one~~first process step; and

etching the recessed bearing surface relative to a second orientation in the ~~either~~second process step.

20. (previously presented): A slider formed from the method of claim 622.

21. (previously presented): A slider formed from the method of claim 1.

22. (new) A method for fabricating a slider comprising the step of:

fabricating a trench in a wafer having a recessed trench surface spaced from a trailing end surface of the slider to form a trailing edge of a raised bearing surface of the slider defined by an etched depth of

the trench of the slider.

23. (new) A head comprising:

a slider having a leading edge, a trailing edge and a media facing surface non parallel to a trailing edge surface of the slider; and

a trench in an overcoat layer and the trench having a side surface non parallel to the media facing surface and spaced from the trailing edge surface a distance determined by an etched depth of the trench measured from the trailing edge surface of the slider.